



(c) bonding said coated copper foil of (b) to an inner layer board having inner wirings on one or both of the faces thereof, said thermosetting resin being laminated onto said inner layer board to form a multi-layer board;

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control
(d) removing said copper foil from the multi-layer board of step (c) by etching with an alkaline etching solution; thereby leaving said alkaline refractory metal exposed;

(e) forming blind via holes in both the alkaline refractory metal and the thermosetting resin by directly irradiating said exposed alkaline refractory metal of (d) to remove the alkaline refractory metal and the thermosetting resin simultaneously with a CO₂ laser to form a multi-layer board in which via holes are formed; and

(f) forming outer wirings.

Please add the following new claim.

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19. A multi-layer printed wiring board having via holes and outer wirings on at least one outer surface of said board, wherein the outer wirings have two metal layers on a thermosetting resin layer, the outer of said layers being of copper and the second of said layers being of an alkaline refractory metal, said via holes having a layer of copper on said thermosetting resin.

REMARKS

Claims 10-19 remain in the application for further prosecution. Claim 10 has been amended and new Claim 19 added.

The drawings have been objected to as being improperly cross hatched. Reconsideration is requested. The present drawings were accepted and issued with the parent of this application, U.S. 6,107,003. A full set of drawings will be submitted if required, but the Applicants believe the original drawings to be preferable. A sample of Figure 1(a) is